



REMARKS

Reconsideration of the above-identified patent application is respectfully requested in view of the attached affidavit and the following remarks. Claims 1 through 20 remain in the application.

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The invention comprises a method for removing a small layer of copper from copper features forming part of a printed circuit board, by using etchants many of which have been used before, but not without removing large quantities of copper. The copper is selectively removed in the present invention by applying an inorganic acid etchant, persulfate and phosphate salts.

The invention has been rejected under 35 U.S.C. 103 (a) as unpatentable over FERRIER et al, in view of DUTKEWYCH et al. This rejection is respectfully traversed for the following reasons:

a) in view of the attached affidavit swearing back of

this reference.

b) FERRIER et al teaches the use of halide ions for treating the copper surfaces, whereas the invention specifically eschews halides, because they remove too much copper. Therefore, FERRIER et al would be considered, by reasonable inference, as an opposite teaching from that of the invention.

c) FERRIER et al is never concerned with removing too much copper, as is the present invention.

d) The invention also generally eschews treatment with alkaline, and FERRIER et al treats the surface with an alkaline.

For all of the above listed reasons, the combination that suggests the use of the primary reference of FERRIER et al is respectfully not tenable. Furthermore, it would not make sense using the further teachings of DUTKEWYCH et al with FERRIER et al, since without limiting the copper removal, these teachings would not produce the intended result. In

other words, the standard of obviousness required by the statute would not be met.

In view of the foregoing remarks, Applicants respectfully request that claims 1 through 20 be allowed and that the application be passed to issue.

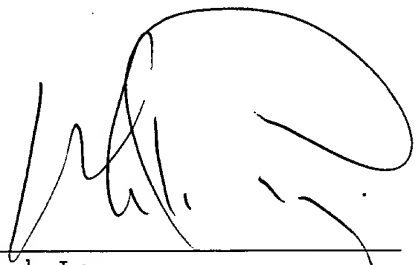
Respectfully submitted,

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